

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT7592926

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEIPING LI	12/26/2021
RECEIVING PARTY DATA	
Name:	YIBU SEMICONDUCTOR CO., LTD.
Street Address:	5045 WAI QING SONG RD., QINGPU DISTRICT
Internal Address:	#20, AREA A, RM. 510
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201700
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17562936
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	YB010-03US
NAME OF SUBMITTER:	JAMIE J. ZHENG/
SIGNATURE:	/Jamie J. Zheng/
DATE SIGNED:	10/17/2022
Total Attachments: 1	
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ASSIGNMENT

WIHEREAS, I, Weiping LI, residing in Shanghai, China, ASSIGNOR, is the sole inventor of the invention in Method for Forming Semiconductor Package and Semiconductor Package, described in an application for a Patent of the United States

- which is executed on even date herewith
- which is identified by Attorney Docket No. YB010-03US
- which was filed on _____, Application No. _____
- which claims priority on U.S. Provisional Patent Application No(s). _____
- I hereby authorize and request my attorney, Jamie J. Zheng, of USCH Law, PC, to insert here in parenthesis (Application number _____, filed _____) the filing date and application number of said application when known.

and WHEREAS, Yibu Semiconductor Co., Ltd., ASSIGNEE, having a place of business at #20, Area A, Rm. 510, 5045 Wai Qing Song Rd., Qingpu District, Shanghai, China 201700, is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, let it be known that for and in consideration of the sum of One Dollar (\$1.00) to me paid, and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention and the said United States provisional application and all United States utility applications that claim priority to said United States provisional application and all divisions, renewals, and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

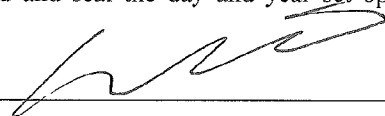
AND I HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my respective signatures.

Date Dec. 26, 2021

Weiping LI  L.S.